ABSTRACT OF THE DISCLOSURE

METHOD FOR ALIGNING OF SEMICONDUCTOR WAFER

Disclosed herein is a method for accurately aligning the position of a semiconductor wafer to accurately transfer the semiconductor wafer to a processing position in an apparatus for manufacturing a semiconductor package.

That is, the present invention provides a method for aligning a semiconductor wafer, implemented in a wafer treatment apparatus such as a singulation apparatus that cuts a semiconductor wafer, on which a plurality of semiconductor packages are arranged in a matrix form, into each semiconductor package, the method characterized in that a vision camera photographs an arrangement relationship between the center of a dowel hole and that of the semiconductor package to accurately determine the position of the wafer in the X-, Y-, and θ directions, thus accurately transferring the wafer to a processing position. Therefore, the method of the present invention can be effectively applied to a method for aligning a new type of wafer such as a wafer-level package. Especially, the method of the present invention can minimize the effect of errors due to vibration of the apparatus, etc. and obtain an accurate measurement value, thus accurately aligning the position of the wafer.

Fig. 10